

MCNI8596-P40 X-Band Internally Matched GaN Device

Key Features

■ Operating Frequency: 8.50-9.60 GHz
 ■ Saturated Output Power (Psat): ≥ 40 dBm

■ Power Gain(Gp): ≥ 8 dB

■ Power-Added Efficiency (η): ≥ 36%
■ Port Metabling: Zin/Zout = 50.0

■ Port Matching: Zin/Zout = 50 Ω



Product Description

The MCNI8596-P40 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 8.50-9.60GHz.

This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	40	V
Gate-Source Voltage	V _{GS}	-5	V
Storage Temperature	Tstg	-65 ~ +150	°C
Channel Temperature	Tch	150	°C

^{*}Not recommended to work under these conditions.

Microwave Electrical Characteristics

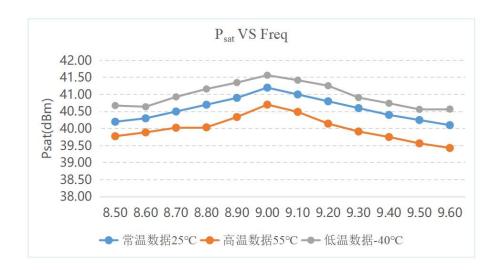
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	dsr	VDS:28V CW Pin: 32dBm Freq: 8.5~9.6GHZ	-	1	-	Α
Saturated Output Power	P _{sat}		40	-	-	dBm
Power Gain	G _p		8	-	-	dB
Power-Added Efficiency	η		36	-	-	%
Gain Flatness	ΔG		-0.8	-	0.8	dB

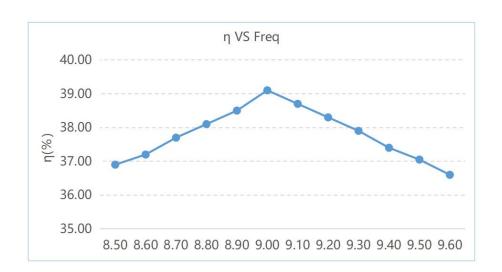


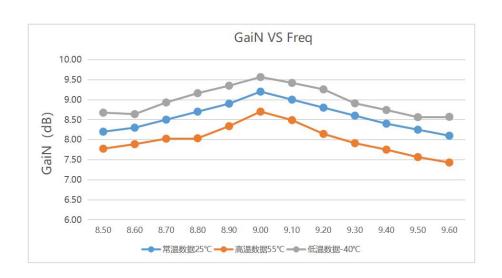
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Typical Curves





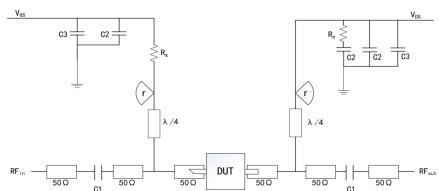




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Recommended Application Circuit



DUT: Device Under Test

C1:1pF Rp:51 Ω C2:1000pF Rg:15 Ω

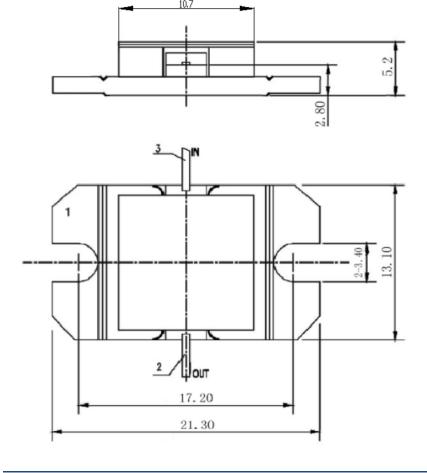
C3:100uF

Radius ≈ 3.5mm (Rogers 5880, 20 mil)

ESD Level

ESD	Class III	2000V
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Overall Dimensions



Using Notes:

- During transportation and storage, ensure proper drying.
- During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.
- When powering on, apply gate voltage first, then apply leakage voltage.

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